12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250815002.1
Qualification of TI Philippines as an additional Assembly site for select package devices
Change Notification / Sample Request

Date: August 15, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250815002.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS563201DDCR	TPS563201DDCR
TPS563201DDCT	TPS563201DDCT
TPS562208DDCR	TPS562208DDCR
TPS563208DDCT	TPS563208DDCT
TPS562201DDCR	TPS562201DDCR
TPS563208DDCR	TPS563208DDCR

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250815002.1	**PCN Date:**	August 15, 2025
Title:	Qualification of TI Philippines as an additional Assembly site for select package devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	November 13, 2025	**Sample requests accepted until:**	October 14, 2025

***Sample requests received after** October 14, 2025 **will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the Qualification of TI Philippines as an additional Assembly site for select package devices. No material differences between sites.

	Current Site	Additional site
Assembly Site	TI Chengdu	TI Philippines

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
TI Chengdu	CDA	CHN	Chengdu
TI Philippines	**PHI**	**PHL**	Baguio City

Sample product shipping label (not actual product label)

Product Affected:

TPS562201DDCR	TPS562208DDCR	TPS563201DDCR	TPS563208DDCR
TPS562201DDCT	TPS562208DDCT	TPS563201DDCT	TPS563208DDCT

Qualification Data

Approve Date 27-MAY -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS562201DDCR	Qual Device: TPS562208DDCR	Qual Device: TPS563201DDCR	Qual Device: TPS563208DDCR	QBS Reference: TPS61378QWRTERQ1	QBS Reference: TPS22995HQDDCRQ1	QBS Reference: ROOMBADRLR	QBS Reference: TPS2117DRLR	QBS Reference: TPS563201DDCR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	2/154/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	3/231/0	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	3/231/0	-	1/77/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	-	-	-	-	-	3/231/0	1/77/0
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	-	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	-	-	3/231/0	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/231/0	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	-	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	3/135/0	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	1/77/0	-	-	-
HTOL	B1	Life Test	150C	408 Hours	-	-	-	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	1/15/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	3/30/0	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	1/3/0	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	1/3/0	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/6/0	1/6/0	1/3/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/10/0	1/10/0	1/10/0	3/90/0	3/90/0	1/30/0	1/30/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/1/0	-	-	-	-	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device TPS562201DDCR is qualified at MSL1 260C
Qual Device TPS562208DDCR is qualified at MSL1 260C
Qual Device TPS563201DDCR is qualified at MSL1 260C
Qual Device TPS563208DDCR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2408-020

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to

be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.